



Material Content Data Sheet



Sales Product Name		ICE3A2065		Issued		20. July 2018		
MA#		MA000981062						
Package		PG-DIP-8-13		Weight*		556.57 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.237	0.40	0.40	4020	4020
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		97	
	non noble metal	zinc	7440-66-6	0.215	0.04		386	
	non noble metal	iron	7439-89-6	4.297	0.77		7720	
wire	non noble metal	copper	7440-50-8	174.475	31.35	32.17	313483	321686
	noble metal	gold	7440-57-5	0.245	0.04	0.04	440	440
	encapsulation	organic material	carbon black	1333-86-4	1.098	0.20		1973
encapsulation	plastics	epoxy resin	-	35.503	6.38		63790	
	inorganic material	silicondioxide	60676-86-0	329.413	59.19	65.77	591862	657625
leadfinish	non noble metal	tin	7440-31-5	7.496	1.35	1.35	13468	13468
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1430	1430
glue	plastics	epoxy resin	-	0.111	0.02		200	
	noble metal	silver	7440-22-4	0.629	0.11	0.13	1131	1331
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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